

Version With Markings To Show Changes Made

Claims 1 and 27 are cancelled and the remaining claims amended as shown below:

1. ~~A method of detaching a film of material from a surface of a substrate, the method comprising engaging an outlet of a fluid delivery device with an aperture in the substrate from the opposite side of the substrate to the surface to which the film is attached, and causing the fluid delivery device to pass a fluid out of the outlet and through the aperture to generate a detaching force between the film of material and the surface of a substrate adjacent to the aperture.~~
2. (Amended) A method according to claim 25 1, further comprising inserting the fluid delivery device through the aperture from the opposite side of the substrate to which the film is attached, and pressing the fluid delivery device against the film to separate the film from the surface of the substrate adjacent to the aperture prior to passing the fluid through the aperture.
3. (Amended) A method according to claim 25 1, wherein a retaining member is positioned against the film on one side of the aperture to cause the film to detach from the substrate on an opposite side of the aperture.
4. (Amended) A method according to claim 25 1, wherein the aperture in the substrate is adjacent the edge portion of the first film.

5. (Amended) Apparatus ~~for detaching a film of material from a substrate, the apparatus comprising a holding device adapted to hold a substrate and according to claim 18, including~~ a fluid delivery device adapted to be coupled to a pressurised fluid source, the fluid delivery device comprising an outlet adapted to be engaged with an aperture in the substrate to deliver fluid from the pressurised fluid source through the aperture, and the fluid delivery device being movably mounted with respect to the holder between an engaged position, in which the outlet engages with an aperture in a substrate held in the holder in use, and a disengaged position in which the outlet is disengaged from an aperture in a substrate mounted in the holder in use.

15. (Amended) Apparatus ~~for removing a film of material from a surface of a substrate, the apparatus comprising a holder adapted to hold a substrate but not a film attached thereto and the holder holding the substrate in a holding plane, according to claim 18, wherein the detachment member is~~ a clamp device comprising two clamp members movable with respect to each other between an open position and a closed position, and the clamp device being movably mounted with respect to the holder for movement between a disengaged position, a clamped position and a removed position; whereby, when a substrate is held in the holder in use, the clamp device, with the clamp members in the open position, is moved from the disengaged position to the clamped position, in which the film is located between the clamp members, and when the clamp device is in the clamped position, the clamp members are moved to the closed position to clamp the film between the clamp members, and the clamp device is then moved from the clamped position to the removed position to remove the film from the substrate.

18. (Amended) Apparatus for ~~removing~~ detaching a film of material from a surface of a substrate, the apparatus comprising a holder adapted to hold a substrate but not a film attached thereto and the holder holding the substrate in a holding plane, an applicator movably mounted with respect to the holder, a supply mechanism for supplying a removal material having an adhesive layer thereon to the applicator, and the applicator moving the removal material detachment member into contact with a film of material attached to a substrate held in the holder to apply the removal material detachment member to the film so that the adhesive layer adheres the removal material to the film attachment force between the detaching member and the film is greater than the adhesion force between the film and the surface of the substrate, and means for pulling moving the removal material detachment member away from the holding plane to remove the removal material detachment member and the film from a substrate held in the holder.

19. (Amended) Apparatus according to claim 18, wherein the removal material detachment member is an adhesive tape.

20. Apparatus according to claim 18, wherein the 19, which includes a supply mechanism comprises comprising a first drum from which the removal material detachment member is unwound for supply to the applicator.

21. (Amended) Apparatus according to claim 18, further comprising a receiving mechanism to receive ~~removal material~~ the detachment member and film removed from the substrate.

22. (Amended) Apparatus according to claim 21, wherein the receiving mechanism comprises a ~~second~~ drum on to which the removed ~~removal material~~ detachment member and film is wound.

23. (Amended) Apparatus according to claim 21, wherein the ~~removal material~~ detachment member is continuous between the supply mechanism and the receiving mechanism.

24. (Amended) Apparatus according to claim 21 15 further comprising a receiving mechanism to receive the detachment member and film removed from the substrate, wherein the pulling moving means is provided by movably mounting one or both of the supply mechanism and the receiving mechanism with respect to the holder.

25. (Amended) A method of removing a film of material from a substrate, comprising according to claim 8, including engaging an outlet of a fluid delivery device with an aperture in the substrate from the opposite side of the substrate to the surface to which the film is attached, and causing the fluid delivery device to pass a fluid out of the outlet and through the aperture to generate a detaching force between the film of material and the surface of a substrate adjacent to the aperture and attaching a detachment member to the film such that the attachment force between the detaching member and the

~~film is greater than the adhesion force between the film and the surface of a substrate, and moving the detachment member away from the surface of the substrate to cause the film to detach from the substrate.~~

27. ~~A method according to claim 26, wherein the detachment member comprises a second film of material which is attached to the exposed side of the first film.~~

28. (Amended) A method according to any of claims 1, 4, 8 or 25 claim 8, wherein the substrate is a substrate for mounting a semiconductor chip thereon.